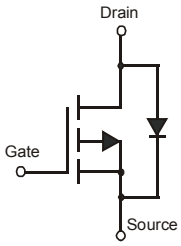
Features

- Low On-Resistance
  - 60mΩ @ V_{GS} = -4.5V
  - 90mΩ @ V_{GS} = -2.5V
  - 113mΩ @ V_{GS} = -1.8V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

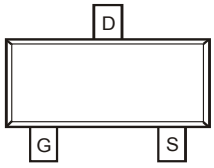
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 e3
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (approximate)

Top View



Internal Schematic



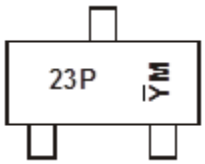
Top View

Ordering Information (Note 4&5)

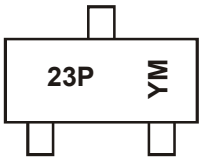
Part Number	Qualification	Case	Packaging
DMP2305U-7	Standard	SOT23	3000/Tape & Reel
DMP2305UQ-7	Automotive	SOT23	3000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/
5. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



Chengdu A/T Site



Shanghai A/T Site

23P = Product Type Marking Code
YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
$\overline{Y}$M = Date Code Marking for CAT (Chengdu Assembly/ Test site)
Y or $\overline{Y}$ = Year (ex: A = 2013)
M = Month (ex: 9 = September)

Date Code Key

Year	2009	2010	2011	2012	2013	2014	2015
Code	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-20	V
Gate-Source Voltage			V_{GSS}	±8	V
Continuous Drain Current (Note 6)	Steady State	T_A = +25°C T_A = +70°C	I_D	-4.2 -3.4	A
Pulsed Drain Current (Note 7)			I_{DM}	-10	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	1.4	W
Thermal Resistance, Junction to Ambient @T_A = 25°C	$R_{\theta JA}$	90	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage		BV_{DSS}	-20	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current	T_J = +25°C	I_{DSS}	—	—	-1.0	µA	V_{DS} = -20V, V_{GS} = 0V
Gate-Source Leakage		I_{GSS}	—	—	±100	nA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage		$V_{GS(th)}$	-0.5	-	-0.9	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance		$R_{DS\ (ON)}$	—	45	60	mΩ	V_{GS} = -4.5V, I_D = -4.2A
				60	90		V_{GS} = -2.5V, I_D = -3.4A
				87	113		V_{GS} = -1.8V, I_D = -2.0A
Forward Transfer Admittance		$\|Y_{fs}\|$	—	9	—	S	V_{DS} = -5V, I_D = -4A
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance		C_{iss}	—	727	—	pF	V_{DS} = -20V, V_{GS} = 0V f = 1.0MHz
Output Capacitance		C_{oss}	—	69	—	pF	
Reverse Transfer Capacitance		C_{rss}	—	64	—	pF	
Gate Resistance		R_G		23		Ω	V_{GS} = 0V, V_{DS} = 0V, f = 1.0MHz
SWITCHING CHARACTERISTICS							
Total Gate Charge		Q_g	—	7.6	—	nC	V_{GS} = -4.5V, V_{DS} = -4V, I_D = -3.5A
Gate-Source Charge		Q_{gs}	—	1.4	—	nC	
Gate-Drain Charge		Q_{gd}	—	1.2	—	nC	
Turn-On Delay Time		$t_{D(on)}$	—	14.0	—	ns	V_{DS} = -4V, V_{GS} = -4.5V, R_L = 4Ω, R_G = 6Ω, I_D = -1A
Turn-On Rise Time		t_r	—	13.0	—	ns	
Turn-Off Delay Time		$t_{D(off)}$	—	53.8	—	ns	
Turn-Off Fall Time		t_f	—	23.2	—	ns	

Notes:
6. Device mounted on FR-4 PCB with 2oz. Copper and test pulse width t ≤ 10s.
7. Repetitive rating, pulse width limited by junction temperature.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to production testing.

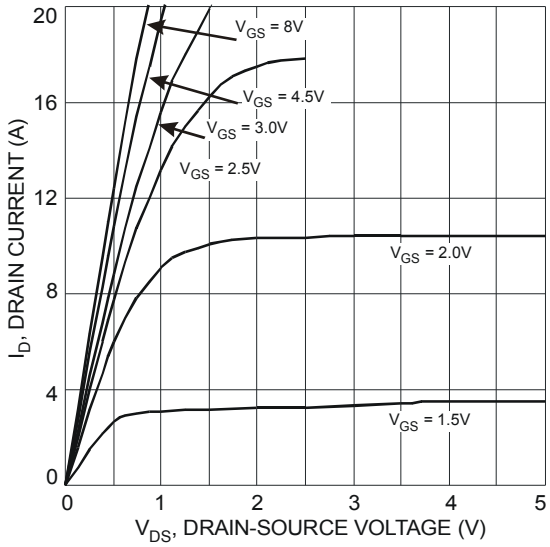


Fig. 1 Typical Output Characteristic

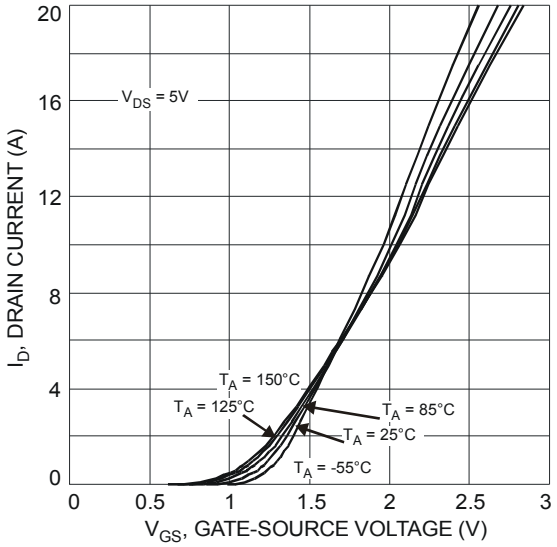


Fig. 2 Typical Transfer Characteristic

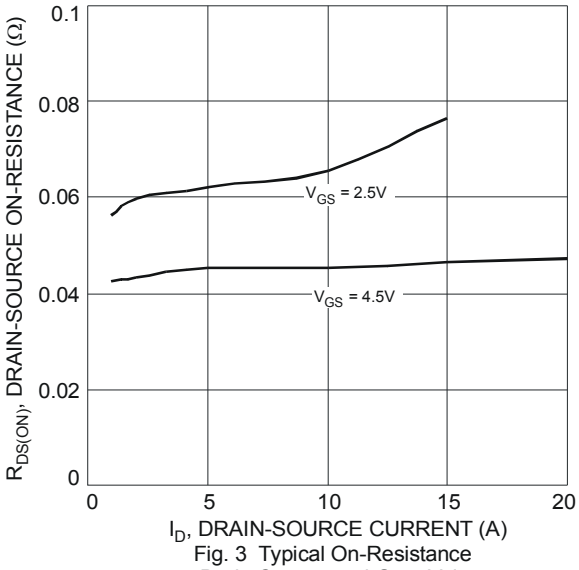


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

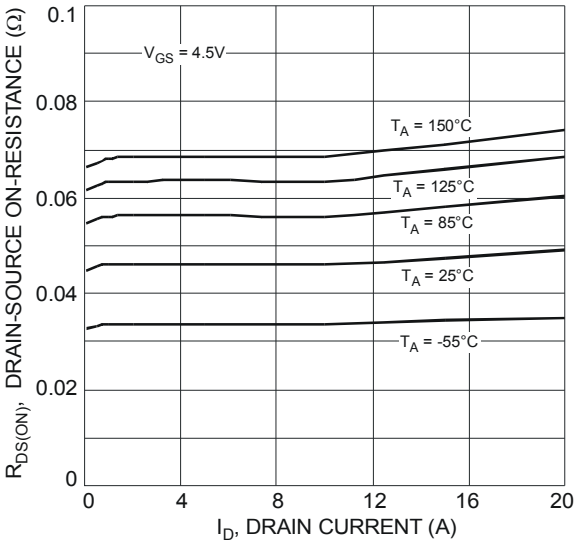


Fig. 4 Typical On-Resistance
vs. Drain Current and Temperature

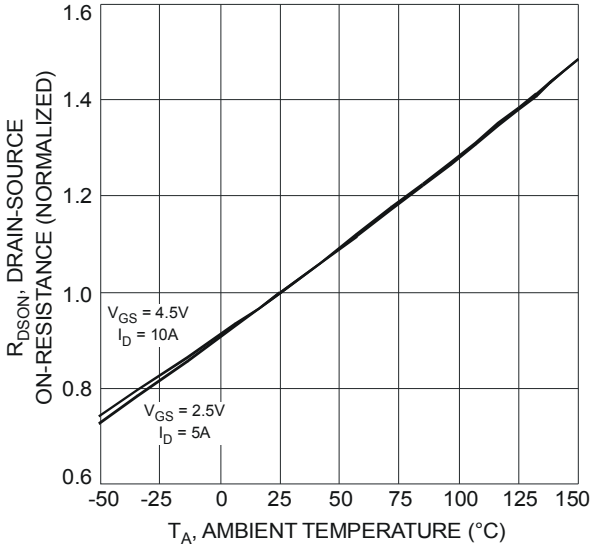


Fig. 5 On-Resistance Variation with Temperature

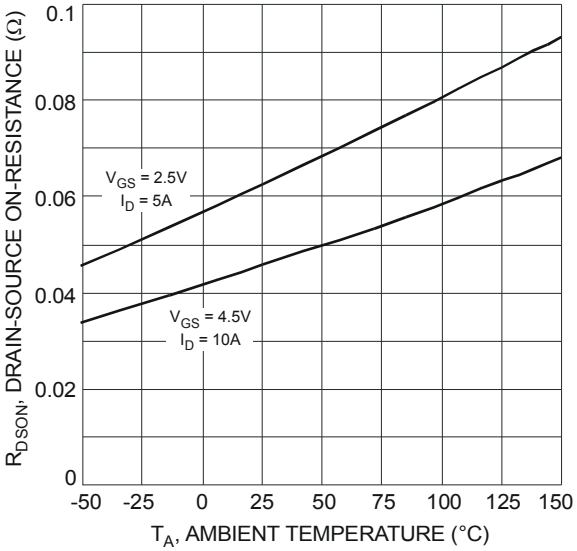


Fig. 6 On-Resistance Variation with Temperature

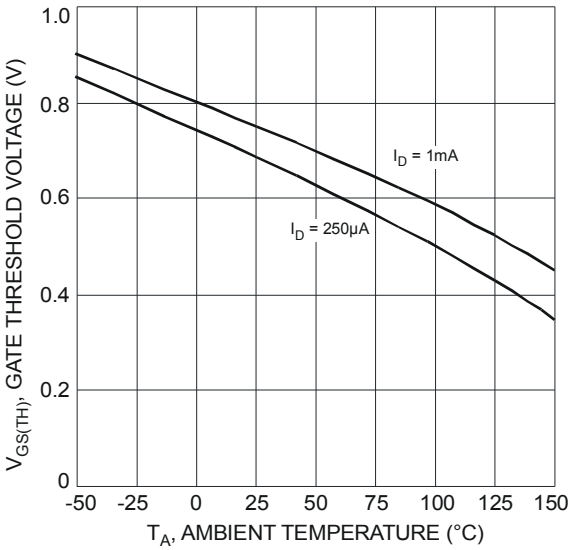


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

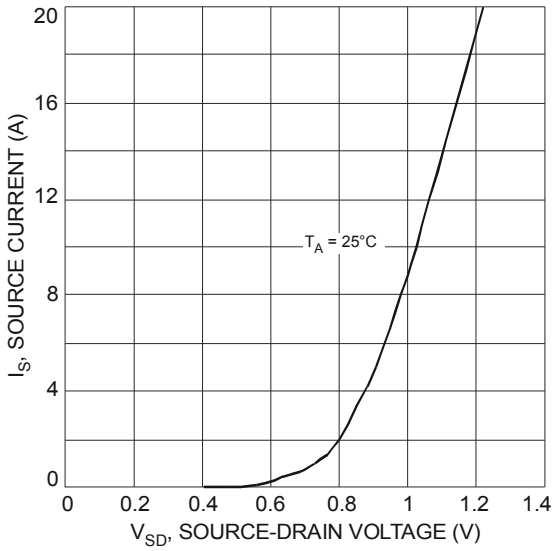


Fig. 8 Diode Forward Voltage vs. Current

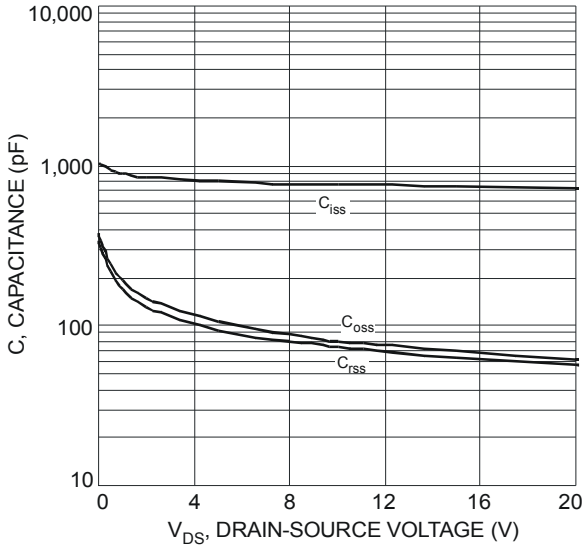


Fig. 9 Typical Total Capacitance

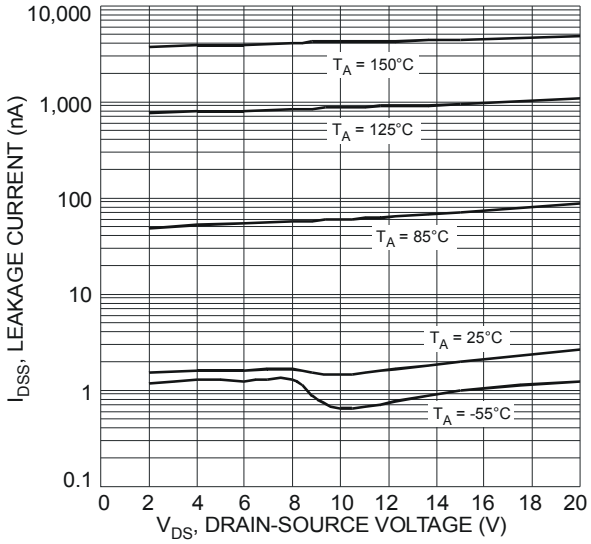


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

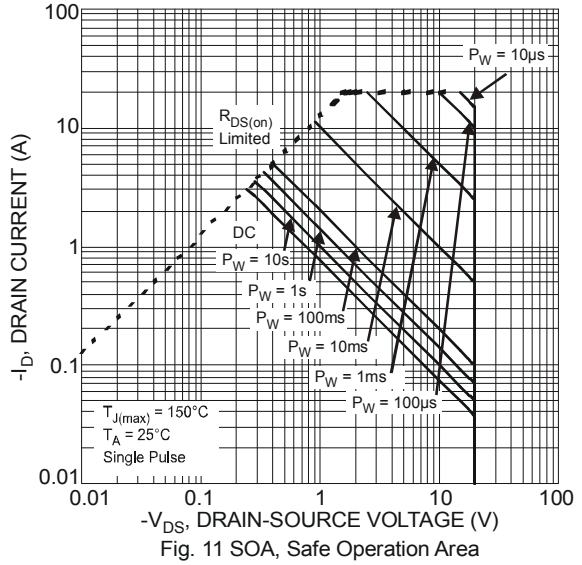


Fig. 11 SOA, Safe Operation Area

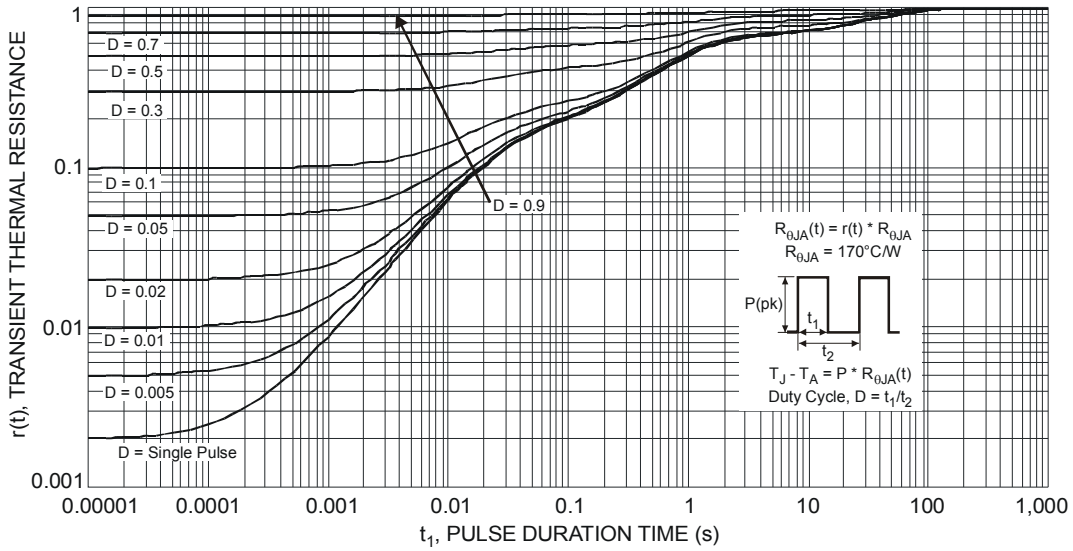
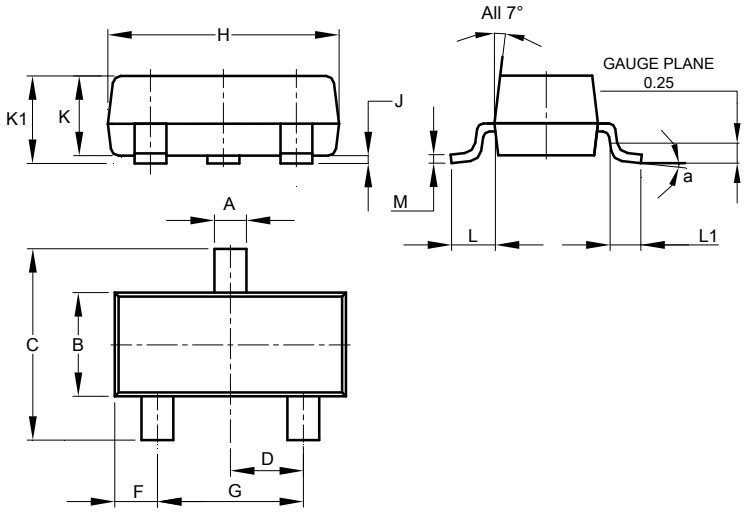


Fig. 12 Transient Thermal Response

Package Outline Dimensions

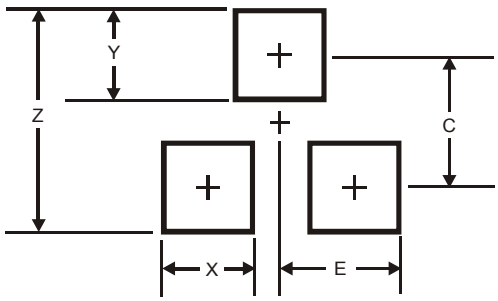
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23			
Dim	**Min**	**Max**	**Typ**
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
α	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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